

## Description

The VSM6N06 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

## General Features

### ● N-Channel

$$V_{DS} = 60V, I_D = 6.3A$$

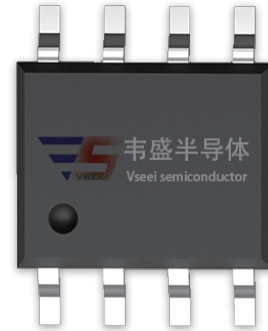
$$R_{DS(ON)} < 30m\Omega @ V_{GS}=10V$$

### ● P-Channel

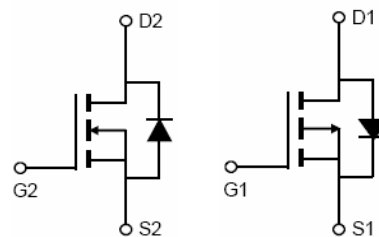
$$V_{DS} = -60V, I_D = -5A$$

$$R_{DS(ON)} < 80m\Omega @ V_{GS}=-10V$$

- High power and current handling capability
- Lead free product is acquired
- Surface mount package



SOP-8



N-channel

P-channel

Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Length	Width	Quantity
VSM6N06-S8	VSM6N06	SOP-8	Ø330mm	12mm		2500 units

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		$V_{DS}$	60	-60	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current	$T_A=25^\circ\text{C}$	$I_D$	6.3	-5	A
	$T_A=70^\circ\text{C}$		4.5	-3.5	
Pulsed Drain Current <sup>(Note 1)</sup>		$I_{DM}$	40	-25	A
Maximum Power Dissipation	$T_A=25^\circ\text{C}$	$P_D$	2.0	2.0	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 To 150	-55 To 150	$^\circ\text{C}$

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	N-Ch	62.5	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	P-Ch	62.5	$^{\circ}\text{C/W}$

## N-CH Electrical Characteristics ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =6A	-	26	30	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =6A	15	-	-	S
Dynamic Characteristics <sup>(Note4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	500	-	PF
Output Capacitance	C <sub>oss</sub>		-	60	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	25	-	PF
Switching Characteristics <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =4.7Ω V <sub>GS</sub> =10V, R <sub>GEN</sub> =3Ω	-	5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	2.6	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	16.1	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	2.3	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =6A, V <sub>GS</sub> =10V	-	25	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	6.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =6A	-	0.8	1.2	V

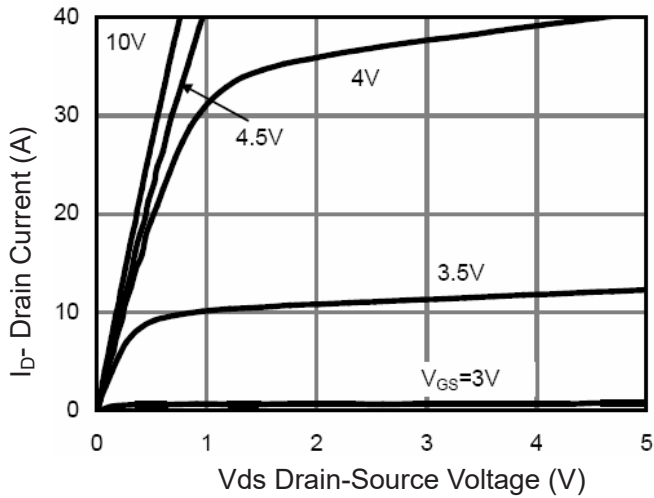
**P-CH Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.5	-2.6	-3.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-5A$	-	64	80	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-15V, I_D=-5A$	16	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	$C_{iss}$	$V_{DS}=-20V, V_{GS}=0V,$ $F=1.0MHz$	-	1450	-	PF
Output Capacitance	$C_{oss}$		-	145	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	110	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-30V, R_L=30\Omega$ $V_{GS}=-10V, R_{GEN}=6\Omega$	-	8	-	nS
Turn-on Rise Time	$t_r$		-	9	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	65	-	nS
Turn-Off Fall Time	$t_f$		-	30	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-30V, I_D=-5A,$ $V_{GS}=-10V$	-	26	-	nC
Gate-Source Charge	$Q_{gs}$		-	4.5	-	nC
Gate-Drain Charge	$Q_{gd}$		-	7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-5A$	-	-	-1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	-5	A

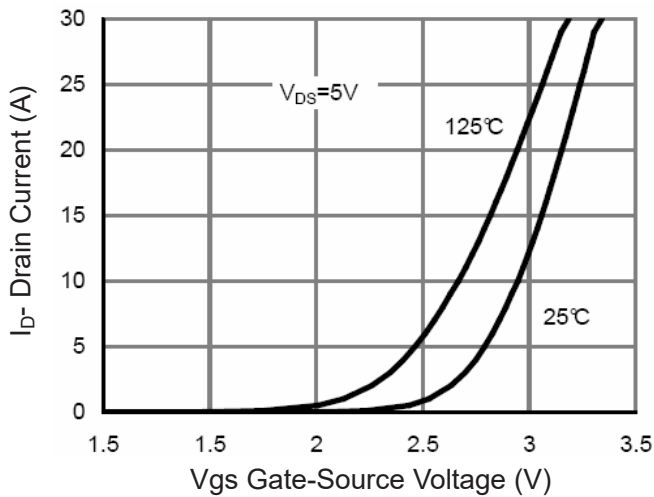
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

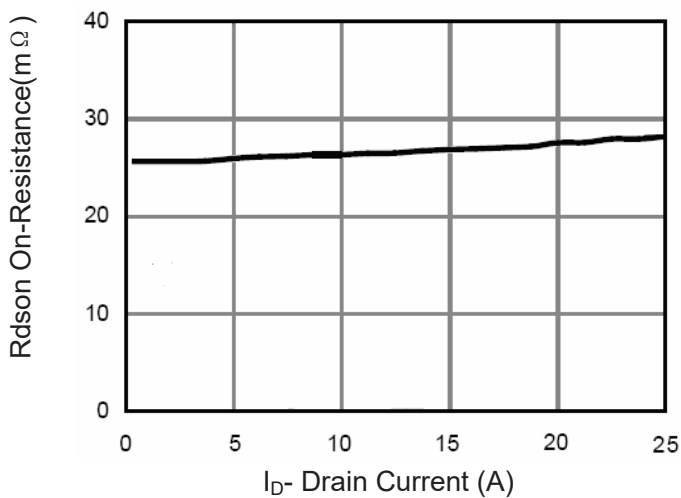
## N-CH Typical Electrical and Thermal Characteristics (Curves)



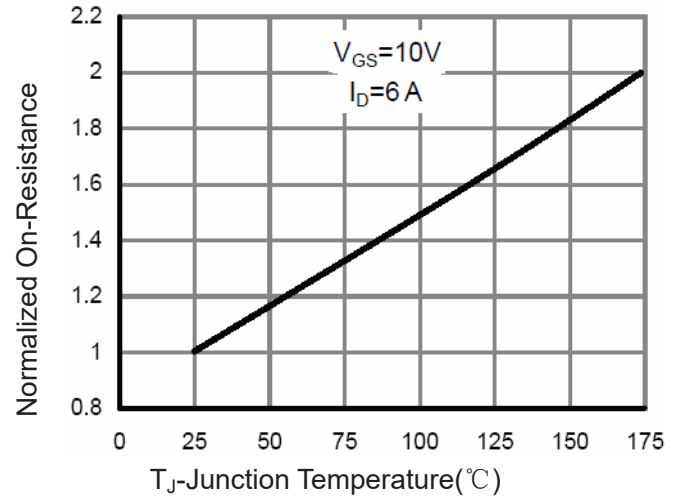
**Figure 1 Output Characteristics**



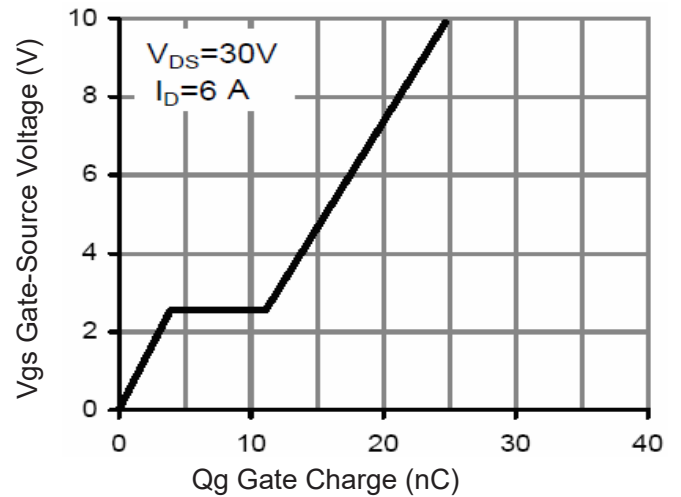
**Figure 2 Transfer Characteristics**



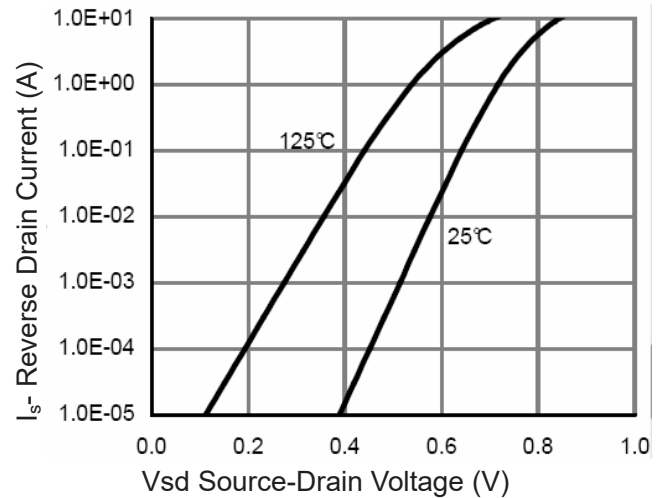
**Figure 3 Rdson- Drain Current**



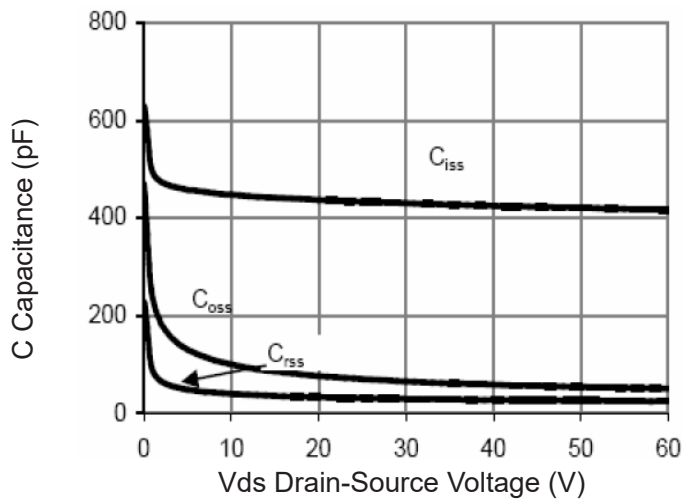
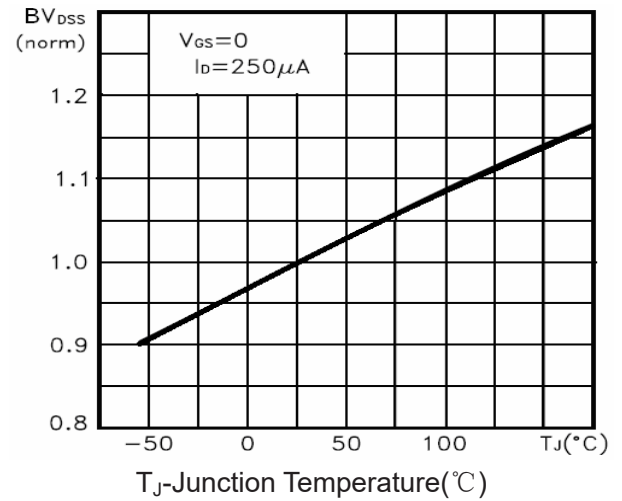
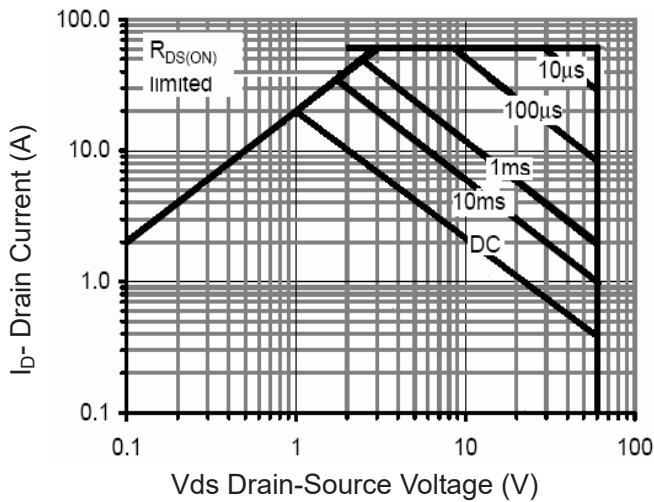
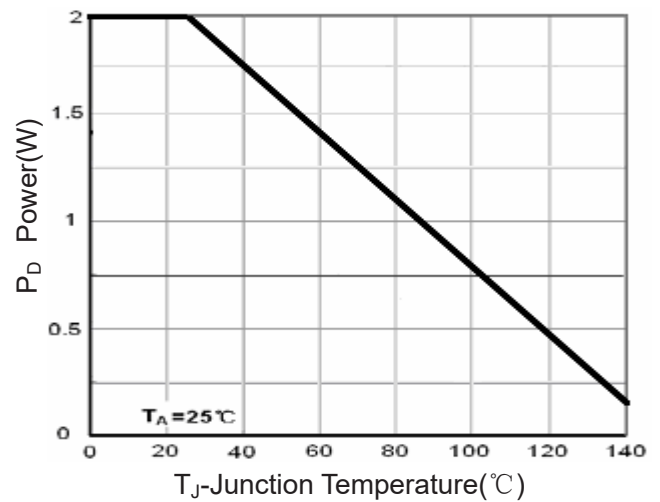
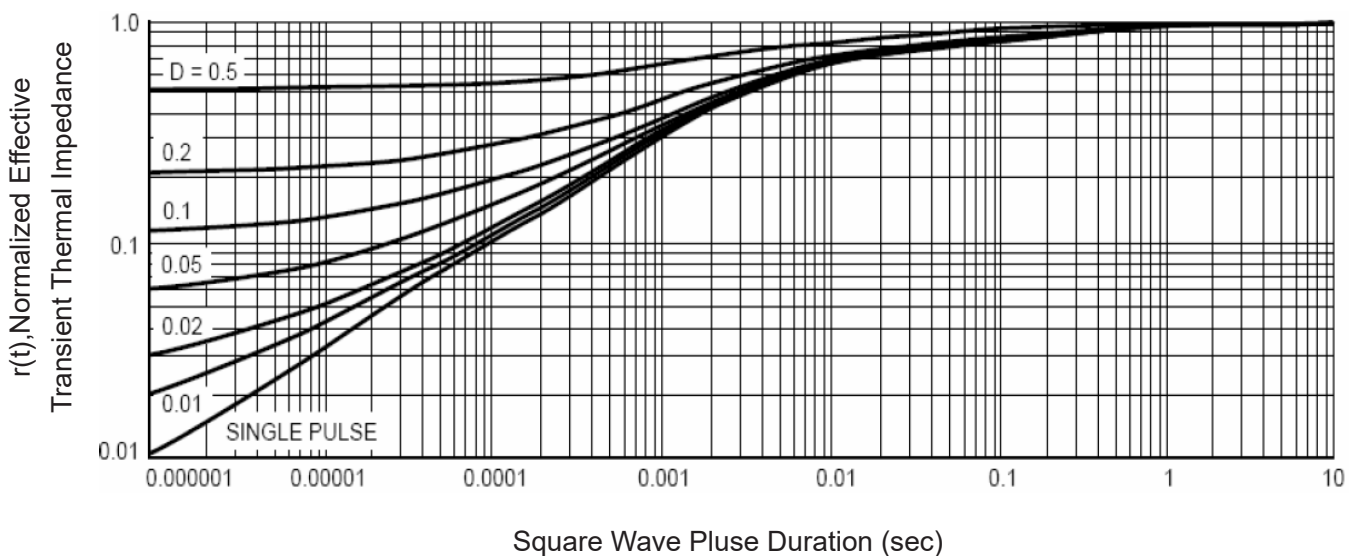
**Figure 4 Rdson-Junction Temperature**



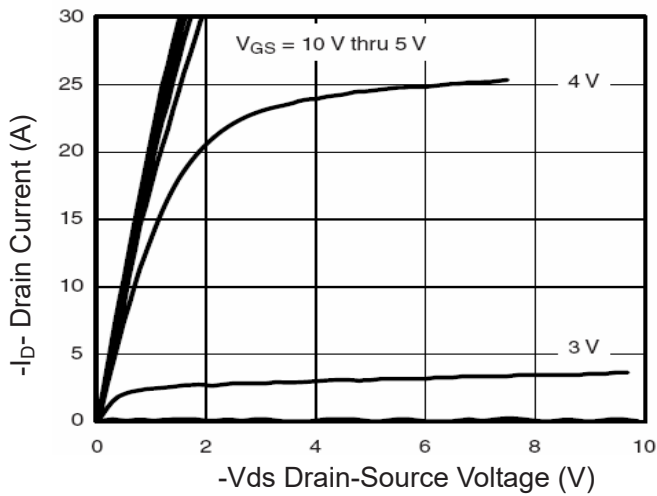
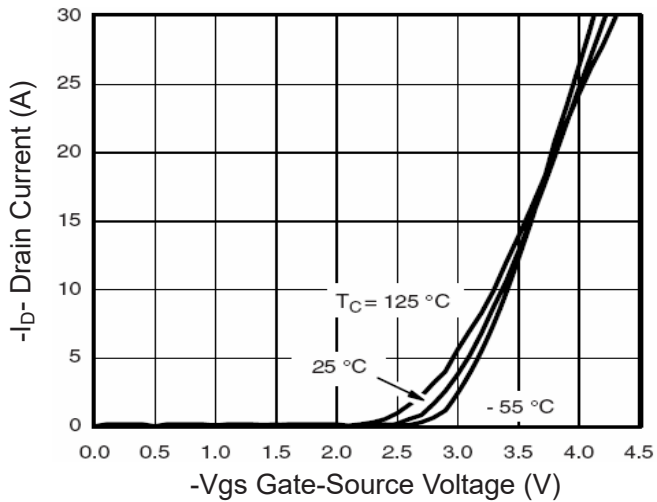
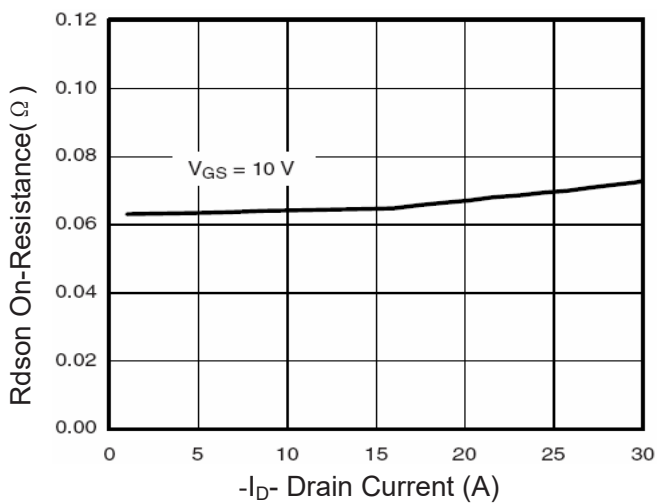
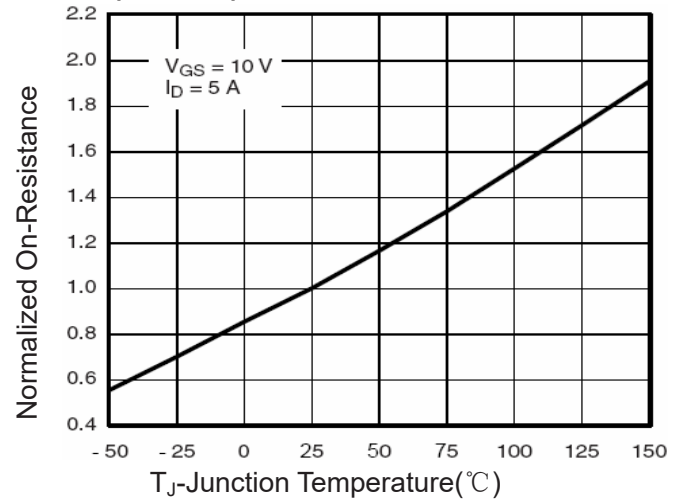
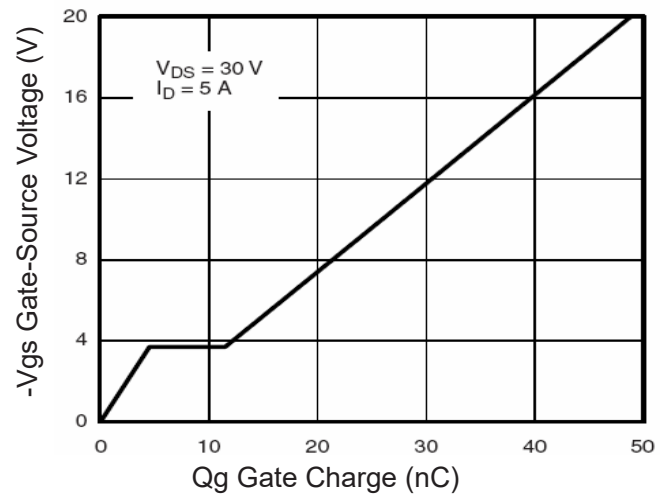
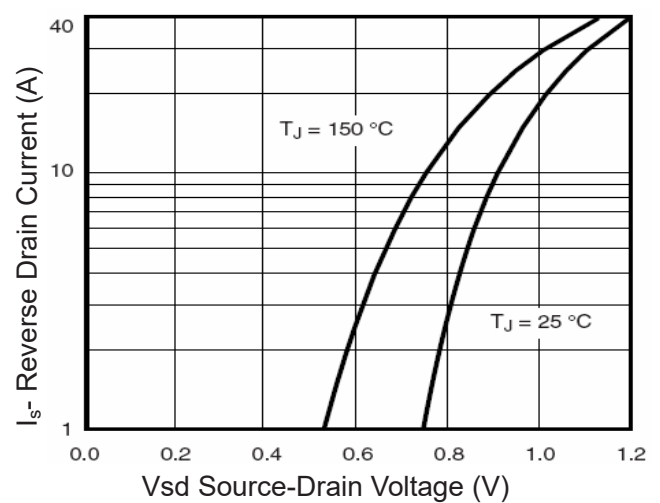
**Figure 5 Gate Charge**

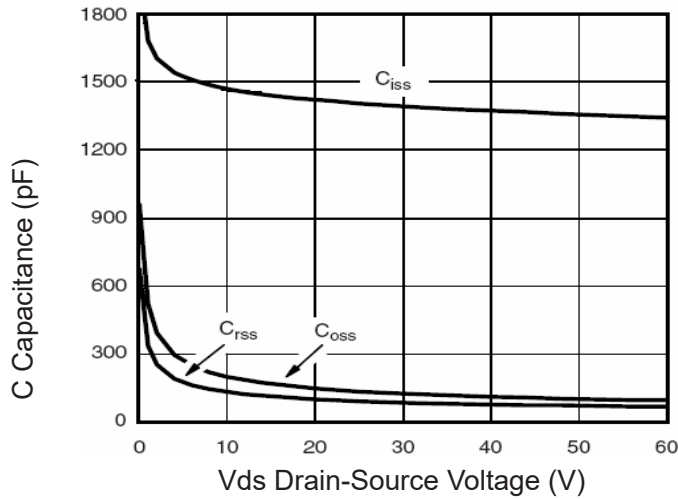
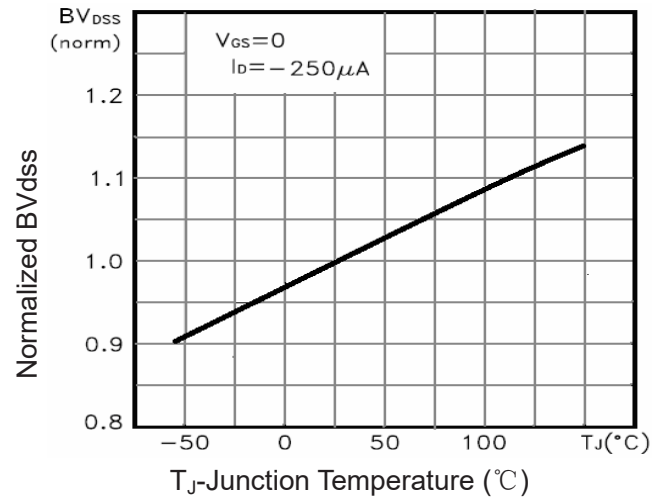
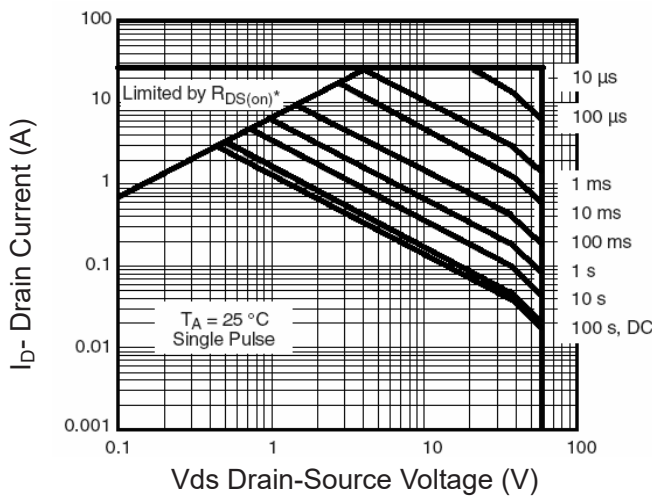
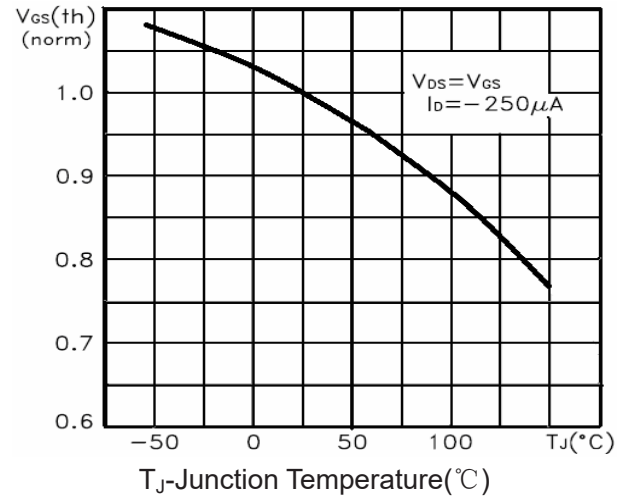
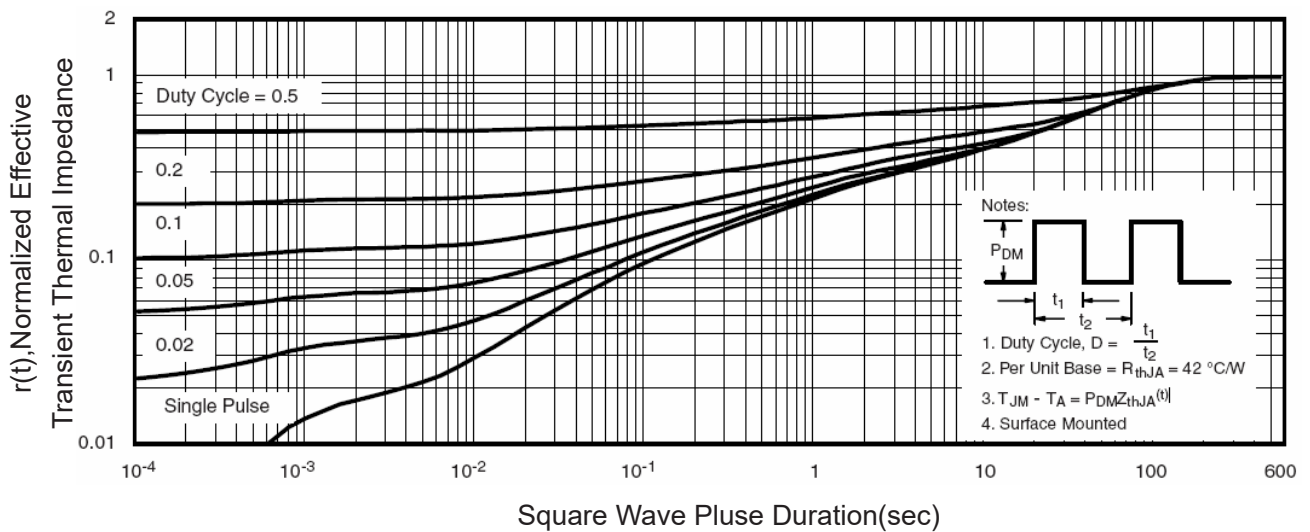


**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9  $BV_{DSS}$  vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10 Power Dissipation**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

# P-CH Typical Electrical and Thermal Characteristics (Curves)


**Figure 1 Output Characteristics**

**Figure 2 Transfer Characteristics**

**Figure 3 Rdson- Drain Current**

**Figure 4 Rdson-Junction Temperature**

**Figure 5 Gate Charge**

**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9 BV<sub>DSS</sub> vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10 V<sub>GS(th)</sub> vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**